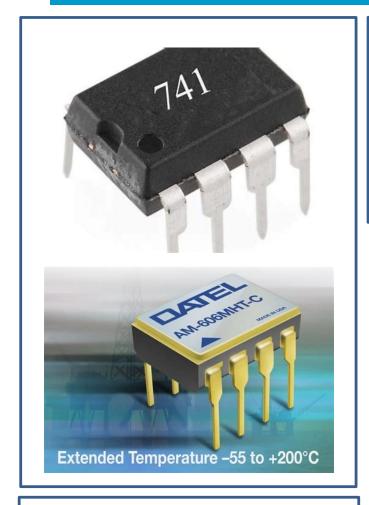
第6讲.运算放大电路B选型



- 1.运放的输入直流误差特性
- 2.运放的交流特性





根据技术要求应首选通用型运放,当通用型运放难以满足要求时,才考虑专用型运放,这是因为通用型器件的各项参数比较均衡,做到技术性与经济性的统一。

虽然专用型运放某项技术参数很突出,但其他 参数则难以兼顾,例如低噪声运放的带宽往往 设计得较窄,而高速型与高精度常常有矛盾, 如此等等。

第6讲.运算放大电路B选型

JAN 1990

卷 24



Ask The Applications Engineer— 6: Op Amp Issues: Why are There so Many Types of Op Amps?

James Bryant

Q. Why are there so many different types of operational amplifier?

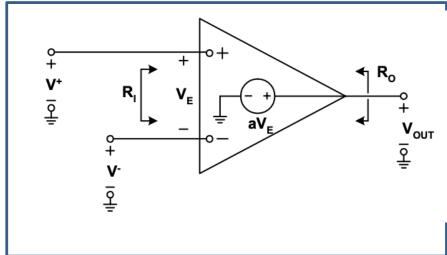
A. Because there are so many parameters that are important in different applications, and because it is impossible to optimize all of them at once. Op amps may be selected for speed, for noise (voltage, current or both), for input offset voltage and drift, for bias current and its drift, and for common-mode range. Other factors might include power: output, dissipation, or supply, ambient temperature ranges, and packaging. Different circuit architectures and manufacturing processes optimize different performance parameters.

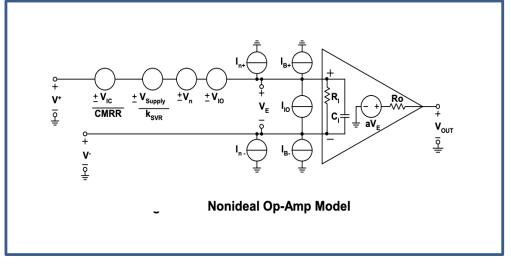
第6讲.运算放大电路B选型

选型表 Operational Amplifiers (Op Amps) | 亚德诺半导体 (analog.com)

可按参数搜索浏览运算放大器,并通过参考设计(Circuits from the Lab®)、设计工具、选型指南、滤波器设计、计算器和运算放大器的LTSpice®/SPICE模型,查找相关设计问题的系统级专家建议。

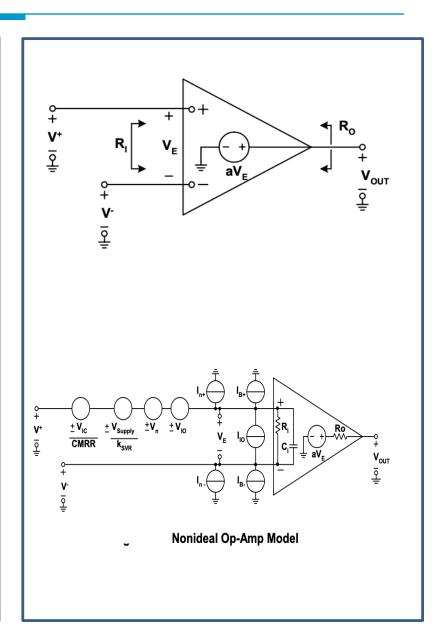


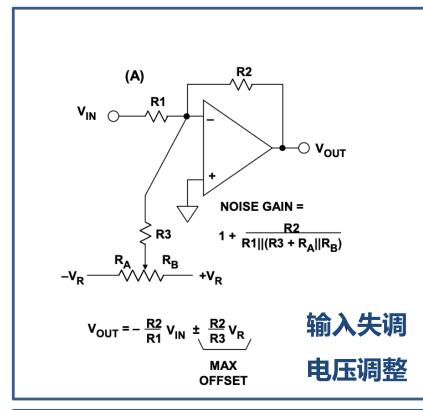


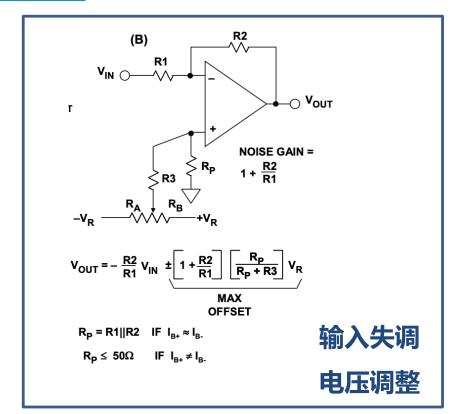


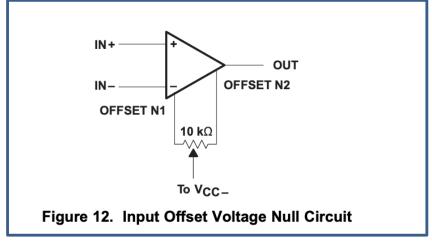
1. 运放的输入直流误差特性

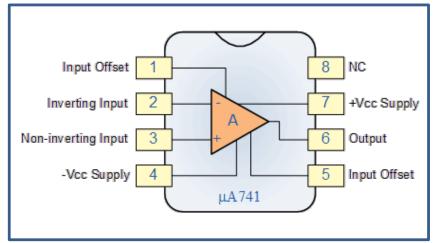
- 1.1、输入失调电压 Vio
- 1.2、输入偏置电流I_{IB}
- 1.3、输入失调电流/0
- 1.4、内部偏置电流抵消电路
- 1.5、偏置电流测量
- 1.6、CMOS运放的失调电流及其成因
- 1.7、JFET运放的失调电流











输入失调电压 V_O:输入电压 为零时,为了使输出电压为零, 在输入端加的补偿电压。

一般约为± (1~10) mV。

超低失调运放为 (1~20) µV。

高精度运放OP-117 V_{IO} =4 μ V。

MOSFET型达20mV。

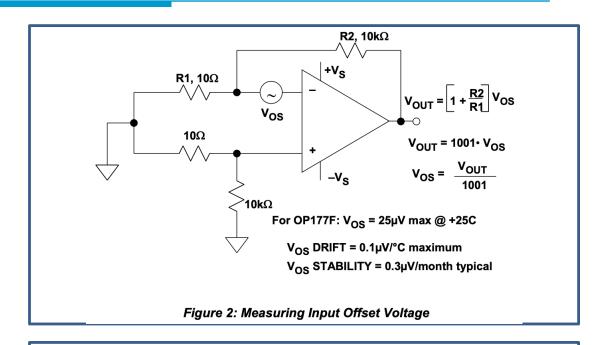
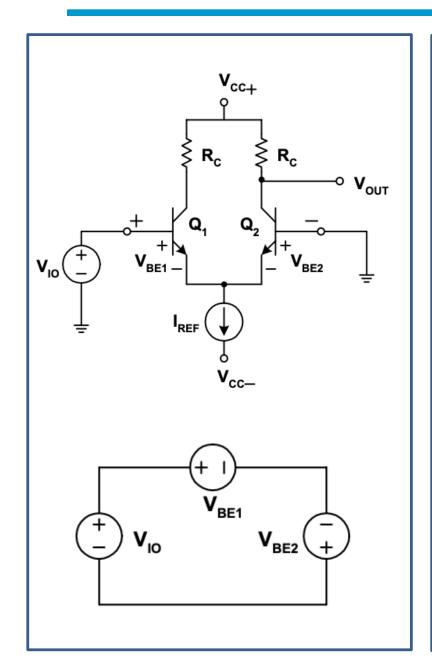


Table 1. Range of Input Offset Voltage and Drift Per Device Process

PROCESS AND DEVICE TYPE	V _{IO} ^{max} at 25°C (μV)	ΔVIO/ΔT [†] (μV/°C)	VIO Full Range (μV)	Long term Drift [†] (μV/month)
Bipolar	150 – 10000	1 – 10	240 – 15000	
LM324	7000		9000	
TLE2021	500	2	750	0.005
THS4001	8000	10	10000	
BiFET	800 – 15000	1 - 30	3000 - 20000	
LF353	10000	10	13000	
TLE2071	4000	3.2	6000	
TL051	3500	8	4500	0.04
CMOS	200 – 10000	<1 – 10	300 - 13000	
TLC071	1000	1.2	1500	
TLV2471	2200	0.4	2400	
TLC2201	200	0.5	300	0.005



$$-V_{IO}+V_{BE1}-V_{BE2}=0$$

$$V_{IO} = V_{BE1} - V_{BE2}$$

$$V_{BE} = \left(\frac{kT}{q}\right) \ln \left(\frac{I_{C}}{I_{S}}\right)$$

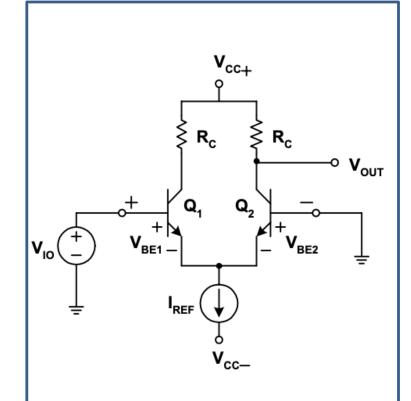
$$V_{IO} = \left(\frac{kT}{q}\right) \ln \left(\frac{I_{C1}}{I_{C2}} \cdot \frac{I_{S2}}{I_{S1}}\right)$$

where the term kT/q is known as the thermal voltage (V_T) ,

I_C is the collector current,

I_S is the reverse saturation current.

1 输入直流误差特性 1.1、输入失调电压 V_{IO}



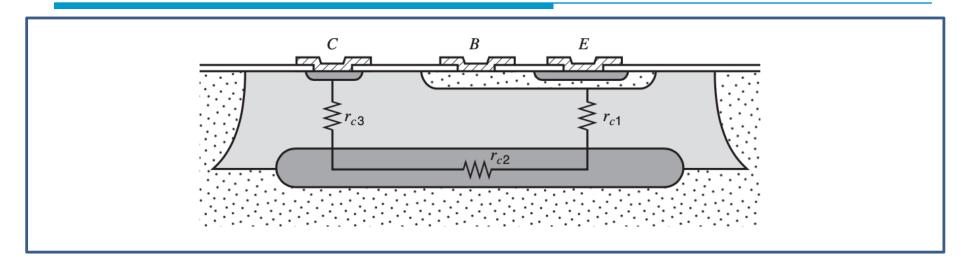
$$V_{IO} = \left(\frac{kT}{q}\right) \ln \left(\frac{I_{C1}}{I_{C2}} \cdot \frac{I_{S2}}{I_{S1}}\right)$$

The errors introduced in equation by the I_C terms are due to the mismatch in the R_C resistors.

The I_S term errors are due primarily to mismatches in the area of the emitter and the width and doping of the base.

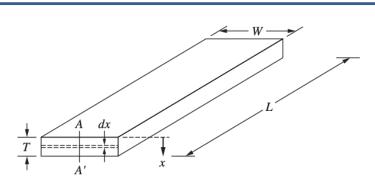
The value of V_T , or kT/q, is material dependent (e.g., 26 mV for silicon) and is inherent in all transistors. This term has the largest impact on V_{IO} and its drift with temperature. As T changes V_{IO} changes, and the change is predictable.

$$V_{IO} = V_{IO}(25^{\circ}C) + \left(\frac{V_{IO}}{T}\right) \cdot \Delta T + \left(\frac{\Delta V_{IO}}{\text{month}}\right) \cdot \text{months}$$



摘:资深的运放设计工程师介绍,两个管子的匹配度在一定范围内是与管子的面积的平方根成正比,也就是说匹配度提高为原来的两倍,面积要增加四倍。当到达一个水平时,即使再增加面积也不会提高匹配度 ,而提高面积是要增加IC的成本。

一个常被使用的办法,就是在运放生产出来后,进行测试,然后再 Trim(可以理解为调校)。这样就能使运放的精度大为提高。当然,测试和Trim都是需要成本,所以精密运放的价格都比较贵。

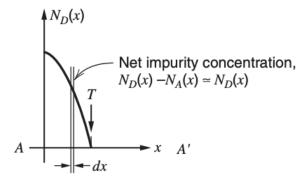


$$R = \left(\frac{1}{q\mu_n N_D}\right) \frac{L}{WT} = \frac{L}{W} \left(\frac{1}{q\mu_n N_D T}\right) = \frac{L}{W} R_{\square}$$

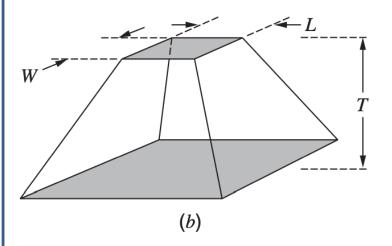
$$R_{\square} = \frac{1}{q\mu_n N_D T} = \frac{\rho}{T}$$

Quantity R_{\square} is the *sheet resistance* of the layer and has units of Ohms.

Impurity concentration, atoms/cm³



$$R = rac{
ho T}{WL} rac{\ln \left(rac{a}{b}
ight)}{(a-b)}$$
 电阻层的梯型扩散



T = thickness of the region

 ρ = resistivity of the material

W, L = width, length of the top rectangle

a = ratio of the width of the bottom rectangle to the width of the top rectangle

b = ratio of the length of the bottom rectangle tothe length of the top rectangle

1 输入直流误差特性 1.1、输入失调电压 Vio: 微调工艺

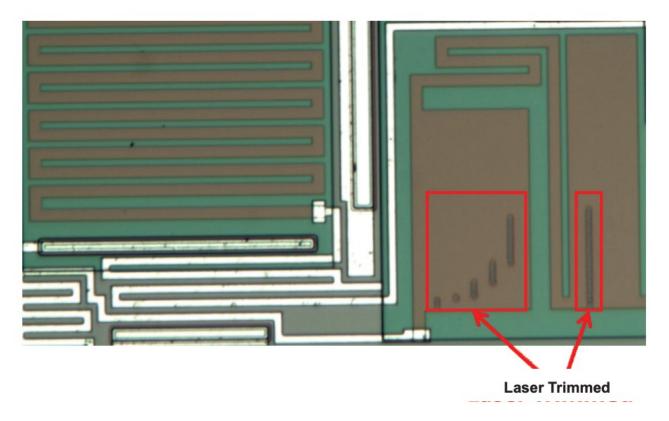
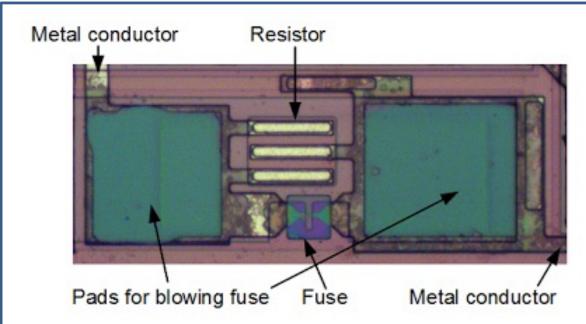


Figure 1. Laser Trimming on Thin-Film Resistors

The highlighted areas show the thin film resistors. During the waferlevel test process, a laser burns away sections of resistive material, thus adjusting its value by increasing the total resistance of the die.

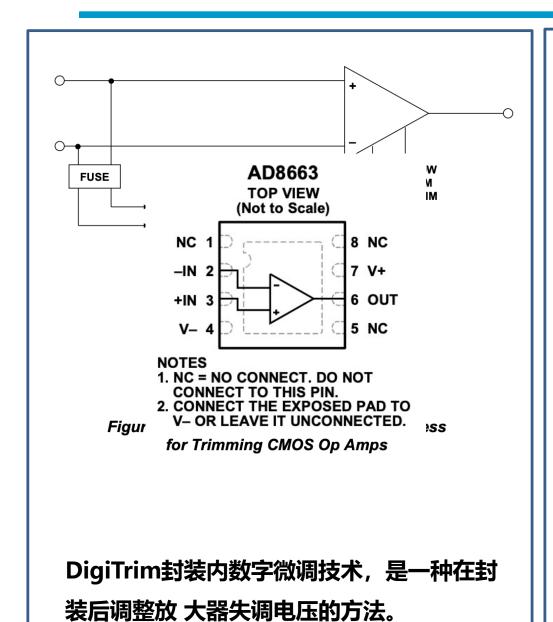
1 输入直流误差特性 1.1、输入失调电压 Vio: 微调工艺



During manufacture of the chips, these fuses can be blown to adjust the resistances to increase the accuracy of the chip.

There is a small resistor (actually two parallel resistors) in parallel with a fuse. Normally, the fuse causes the resistor to be bypassed. During manufacture, the characteristics of the chip can be measured. If more resistance is required, two probes contact the pads and apply a high current. This will blow the fuse, adding the small resistance to the circuit. Thus, the resistance in the final circuit can be slightly adjusted to improve the chip's accuracy.

1 输入直流误差特性 1.1、输入失调电压 Vo: 微调工艺



The DigiTrim[™] CMOS op amp family exploits the advantages of digital technology, so as to minimize the offset voltage normally associated with CMOS amplifiers. Offset voltage trimming is done after the devices are packaged. A digital code is entered into the device to adjust the offset voltage to less than 1 mV, depending upon the grade. Wafer testing is not required, and the patented **Analog Devices' technique called** DigiTrim[™] requires no extra pins to accomplish the function.

1 输入直流误差特性 1.1、输入失调电压 Vio: 微调工艺

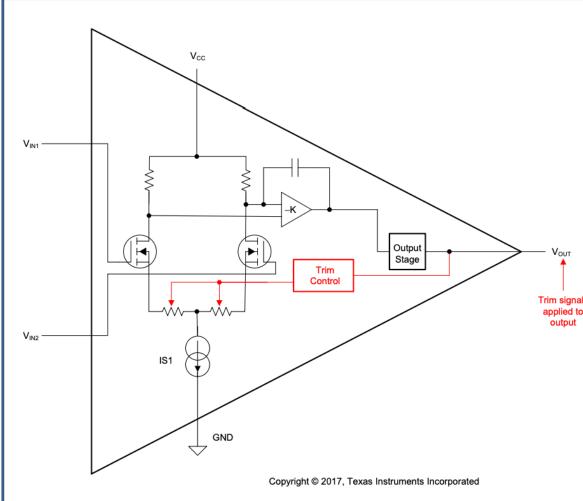
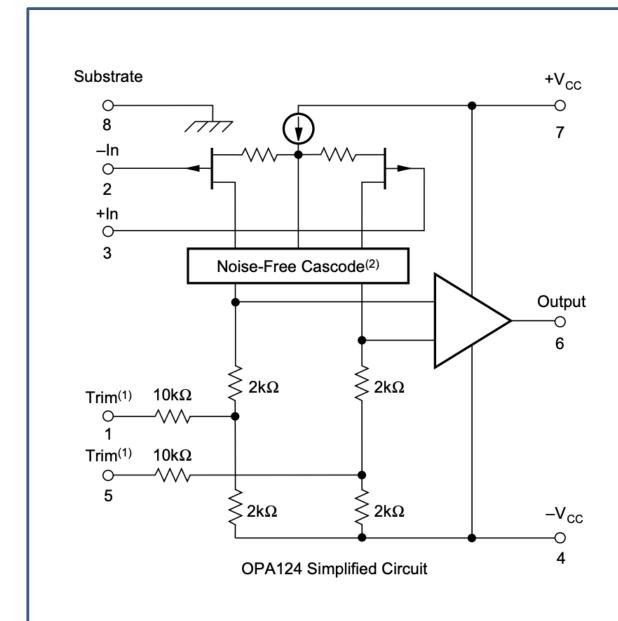


Figure 2. Package-Level e-Trim

Another method used to achieve low offset voltage and drift is e-Trim, which is TI's patented trimming architecture implemented after device packaging. Correction current sources internal to the devices are adjusted during the final packagelevel manufacturing test. Once the trimming is completed, the gateway to trim circuitry is closed, so the trim control circuit is disabled and the adjustments become permanent.

1 输入直流误差特性 1.1、输入失调电压 Vo: 微调工艺

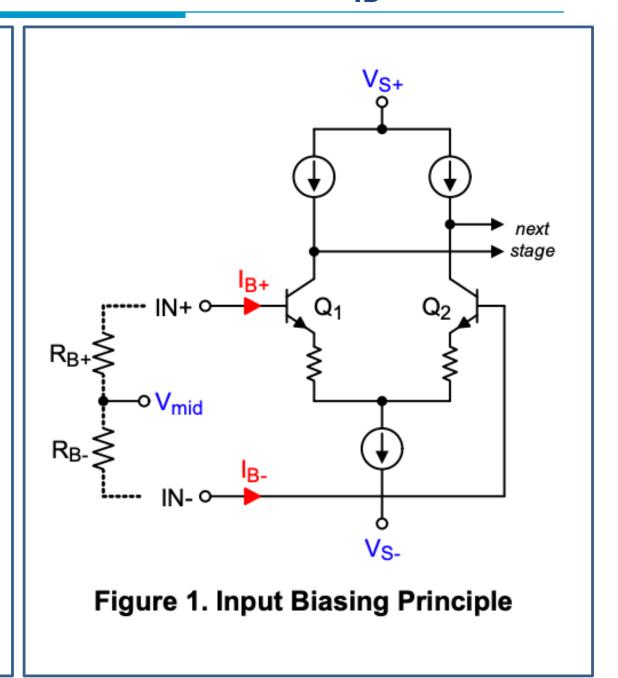


激光微调的Difet输 入电路提供了高精度 和低噪声性能,可与 最好的双极输入运算 放大器相媲美。

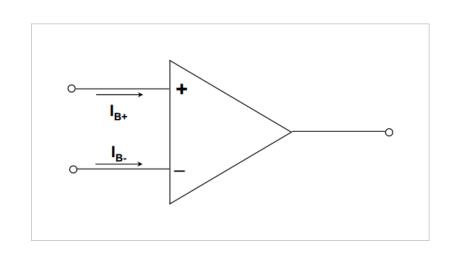
1 输入直流误差特性 1.2、输入偏置电流IIB

对于BJT来说,由于三极管 工作在放大区是需要提供一 定的偏置电流的,因此需要 提供输入电流,一般有nA到 uA级别。

对于MOSFET来说,虽然场效应管本身是场控器件,还是存在一定的漏电流,一般是fA或者pA级别。



1 输入直流误差特性 1.2、输入偏置电流I_{IB}



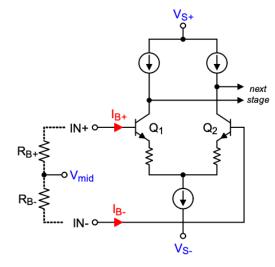
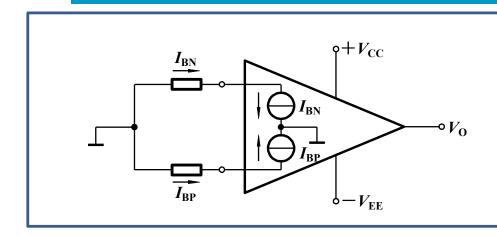


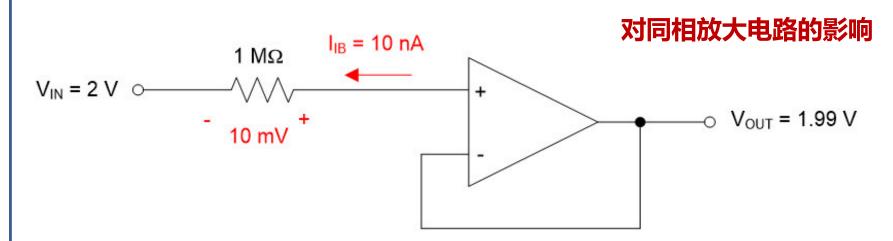
Figure 1. Input Biasing Principle

- ·运放偏置电流IB是一个变化的参数;
- ・随着器件不同,运放偏置电流I_B可能从60fA (毎3us流过 1 个电子) 到数个微安级别;
- •一些运放结构具有匹配的IB, 一些运放IB不匹配;
- ·有些运放中的I。随着温度变化很小,但是FET运放的I。随着温度每升高 10℃, I。增加一倍;
- •一些复杂结构(偏置补偿或者电流反馈运放)内部有不同电流源,对应的偏置电流是 双向流动的;

1 输入直流误差特性 1.2、输入偏置电流I_{IB}



偏置电流是使得运放的输入级能 够正常工作的注入的电流。那么 它有什么影响呢?



在一些高输出内阻的传感器信号放大电路中中,失调电流可能会引起额外问题 ,如果放大电路外部使用的电阻是百kΩ级以上,那么在运放输出端将会产生 新的电压失调误差。

LM358的偏置电流

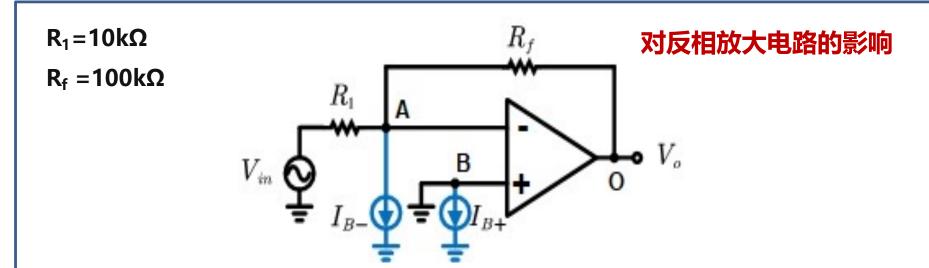
Family Comparison

Talling Companion								
Specification	LM358B LM358BA	LM2904B LM2904BA	LM358 LM358A	LM2904	LM2904V LM2904AV	LM258 LM258A	LM158 LM158A	Units
Supply voltage	3 to 36	3 to 36	3 to 30	3 to 26	3 to 30	3 to 30	3 to 30	V
Offset voltage (max, 25°C)	±3 ±2	± 3 ± 2	±7 ±3	± 7	±7 ±2	±5 ±3	±5 ±2	mV
Input bias current (typ / max)	10 / 35	10 / 35	20 / 250 15 / 100	20 / 250	20 / 250	20 / 150 15 / 80	20 / 150 15 / 50	nA
Gain bandwidth product	1.2	1.2	0.7	0.7	0.7	0.7	0.7	MHz
Supply current (typ, per channel)	0.3	0.3	0.35	0.35	0.35	0.35	0.35	mA
ESD (HBM)	2000	2000	500	500	500	500	500	V
Operating ambient temperature	-40 to 85	-40 to 125	0 to 70	-40 to 125	-40 to 125	-25 to 85	-55 to 125	°C

(1) For all available packages, see the orderable addendum at the end of the data sheet.

INPUT BIAS CURRENT							
I _B Input bias current	V = 1.4 V	LM358		-20 -25)		
			$T_A = 0$ °C to 70°C	-50			
	V _O = 1.4 V	LM358A		-15 -10	nA		
			T _A = 0°C to 70°C	-20			
		1					

1 输入直流误差特性 1.2、输入偏置电流I_{IB}



理想情况下,由于虚断, $I_{B+}=I_{B-}=0$,从而输出增益为 $-R_f/R_1$ 。 假定bias电流大小为100nA(比如LM358的Bias电流最大就是100nA) 。

根据叠加定理,单独分析两个电流源的影响, V_{in} 视为短路。由于B点直接接地,再根据虚短,A点电位也为0,因此流经 R_1 上电流为0,从而流经 R_f 的电流为 I_{B-} 。故由于偏置电流的存在。

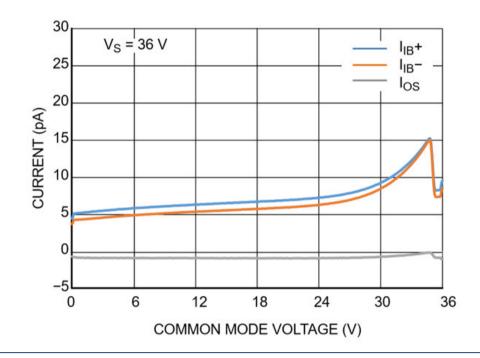
输出电压误差 I_{B-}R_f=100nA*100kΩ=10mV。

1 输入直流误差特性 1.3、输入失调电流 40

INPUT	BIAS CURRENT						
I _B Input bias current	V _O = 1.4 V	1.14250		-20	-250	nA	
		LM358	T _A = 0°C to 70°C		-500		
		1.84250.4		-15	-100		
		LM358A	T _A = 0°C to 70°C		-200		
I _{OS} Input offset current	V _O = 1.4 V	LMOFO		2	50		
		LM358	T _A = 0°C to 70°C		150		
		1.84050.6		2	30	nA	
		LM358A	T _A = 0°C to 70°C		75		

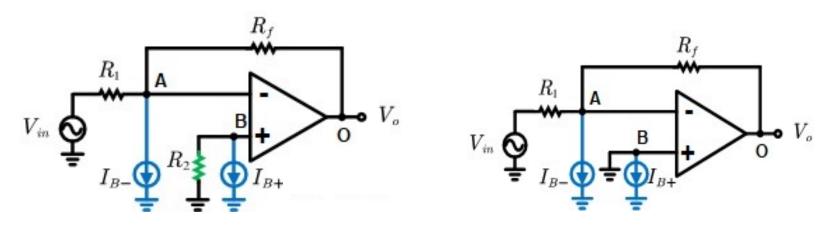
偏置电流这两个值都会有一定的偏差,这个偏差就叫做输入失调电流(Input

offset current)



1 输入直流误差特性 1.3、输入失调电流 40

单独求解电路中 I_{B+}和 I_{B-} 对输出的响应:



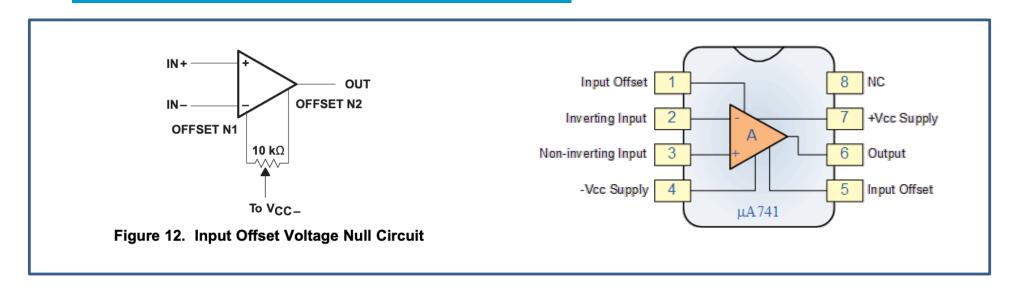
$$V_{o\Delta} = I_B^+ \cdot R_2 \cdot \left(1 + rac{Rf}{R_1}
ight) - I_B^- \cdot R_f = I_B^+ R_f R_2 (rac{1}{R_1 || R_f}) - I_B^- R_f$$

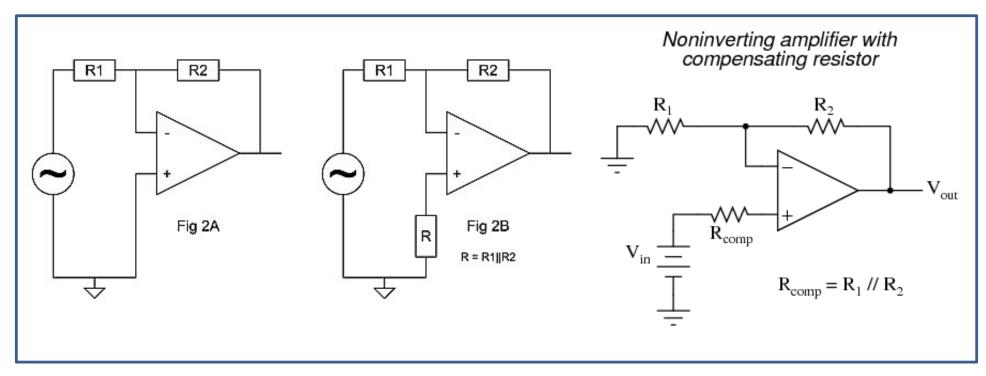
如果 R₂=R₁||R_f,则有:

一般来说,由于电路的对称性,理想情况下, $I_{B+}=I_{B-}$,从而通过补偿电阻的引入,消除了由于偏置电路造成的输出误差。

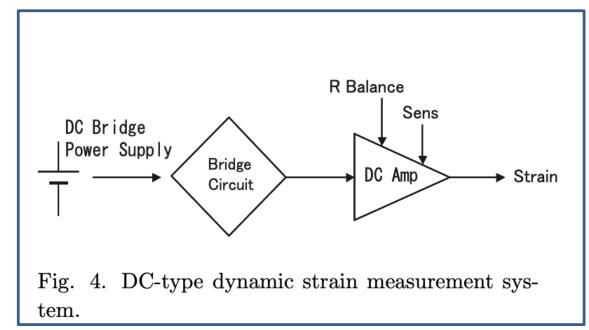
注意:对于偏置电流不匹配的运放,这种外部匹配电阻的使用非但不起作用,有可能会使误差变得更糟。

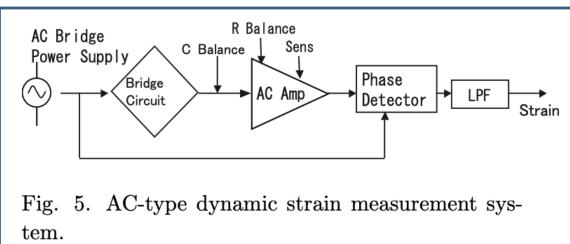
常用电路: 失调电压调整和偏置电流补偿





常用电路: 应变电桥测量电路的直流激励和交流激励





70年代中期之前的应变仪几 乎全部采用载波电桥,其主 要原因是制做高稳定的直流 放大器比较困难。设计电压 增益几千倍,甚至上万倍的 直流放大器,并要求折合到 输入端的漂移在uv级,这在 当时是做不到的要求。

交流放大电路是隔直流的。 放大器的零点漂移不造成系 统误差,并且载波方式的抗 干扰能力强。

常用电路: 应变电桥测量电路的直流激励和交流激励

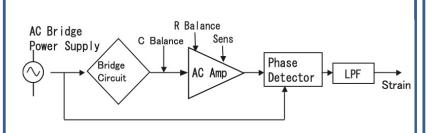
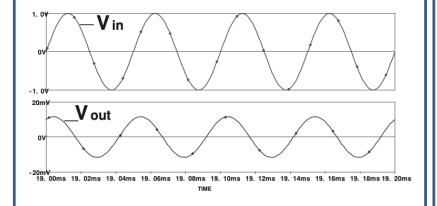
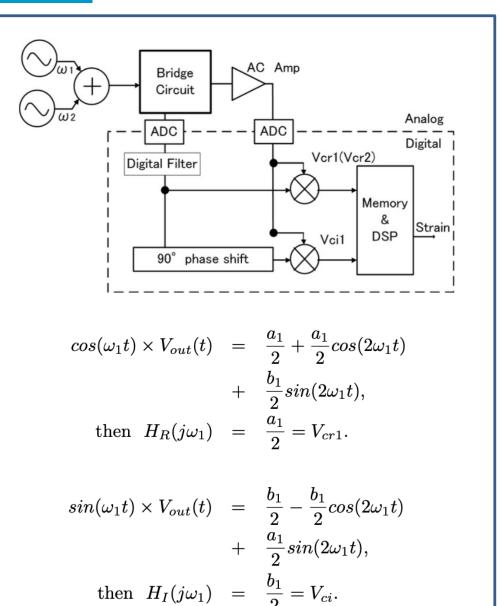


Fig. 5. AC-type dynamic strain measurement system.



交流放大电路是隔直流的。放大器的零点漂移不造成系统误差, 并且载波方式的抗干扰能力强。

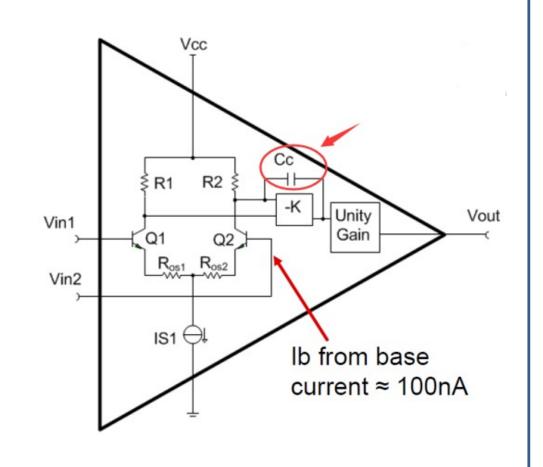


2.运放的交流特性

- 2.1. 增益带宽积 gain-bandwidth product (GBP)
- 2.2.转换速率(摆率) S_R

放大器处理幅值大于等于 100mV的交流大信号时, 应当使用压摆率参数评估 信号带宽。

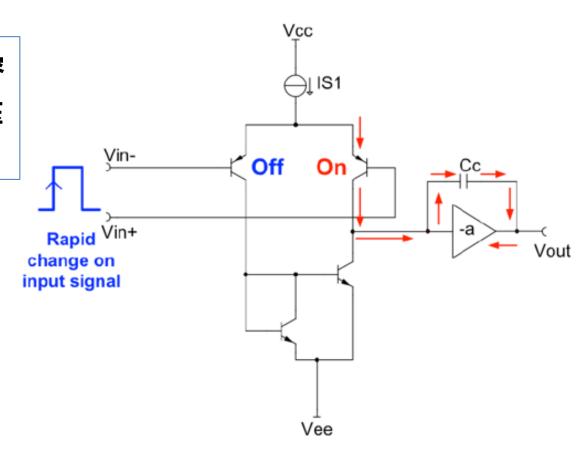
处理幅值小于100mV的交流小信号时,需要通过增益带宽积参数评估信号带宽



增益带宽积和转换速率(摆率) S_R

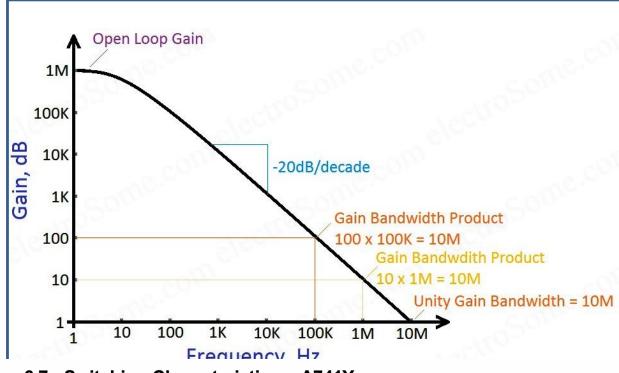
从运放内部看,对主极点电容 Cc充放电的电流大小决定了压 摆率的值。

在小信号输入时(通常 100mVpp 以内), 充放电的电 流跟输入信号的幅度是线性 的关系, 此时输出信号上升 和下降的时间并不是用压摆 率SR来计算的。



当输入信号为大信号时,充放电电流增大以至于被限制在最大值,类似于一个电容被恒流充电,那么电容的输出电压就是斜着线性上升,此时上升下降时间要用压摆率 SR 来计算。

2.1. 开环差模电压增益 A_{10} 和带宽BW



对于电压反馈型运放 来说,有带宽增益积 的概念,观察电压反 馈型运放的开环增益 曲线,从主极点以后 ,带宽和增益的乘积 几乎是一个常数。

6.7 Switching Characteristics: μΑ741Υ

over operating free-air temperature range, $V_{CC\pm} = \pm 15 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _r	Rise time	$V_L = 20 \text{ mV}, R_L = 2 \text{ k}\Omega$		0.3		μs
	Overshoot factor	C _L = 100 pF; see Figure 1		5%		
SR	Slew rate at unity gain	$V_I = 10 \text{ V}, R_L = 2 \text{ k}\Omega$ $C_L = 100 \text{ pF}; \text{ see Figure 1}$		0.5		V/µs

一个放大器的GBP为1GHZ。如果它的增益为+2V/V。那么带苋

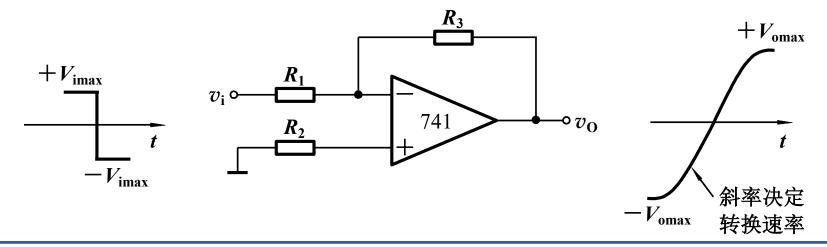
=1G÷2=500M。如果它的增益为+4V/V,那么带宽=1G÷4=250MHz。

2.2. 转换速率 SR

放大电路在闭环状态下,输入为大信号(例如阶跃信号)时,输出电压对时间的最大变化速率,即

$$S_{\rm R} = \frac{\mathrm{d}v_{\rm o}(t)}{\mathrm{d}t}\bigg|_{\rm max}$$

若信号为 $v_i = V_{im} \sin 2\pi f t$,则运放的 S_R 必须满足 $S_R \ge 2\pi f_{max} V_{om}$



S_R是大信号和高频信号工作时的重要指标,

一般通用型运放 S_R 在 $1V/\mu s$ 以下,741的 $S_R = 0.5V/\mu s$

高速运放要求 $S_R > 30V/\mu s以上。$

目前超高速的运放如AD9610的 $S_R > 3500V/\mu s$ 。